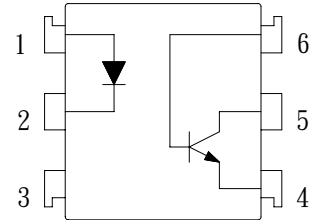


● Description

The K2010 series consist of an infrared emitting diode, optically coupled to a phototransistor detector. They are packaged in a 6-pin DIP package and available in wide-lead spacing and SMD option.

● Schematic



1. Anode
2. Cathode
3. NC
4. Emitter
5. Collector
6. Base

● Features

1. Current transfer ratio
(CTR : Min. 60% at $I_F=2\text{mA}$ $V_{CE}=5\text{V}$)
2. High isolation voltage between input and output
(Viso : 5000Vrms)
3. Pb free and RoHS compliant
4. MSL class 1
5. Agency Approvals
 - UL Approved (No. E169586): UL1577
 - c-UL Approved (No. E169586)
 - VDE Approved (No. 101347): DIN EN60747-5-5
 - FIMKO Approved: EN60065, EN60950, EN60335
 - SEMKO Approved: EN60065, EN60950, EN60335

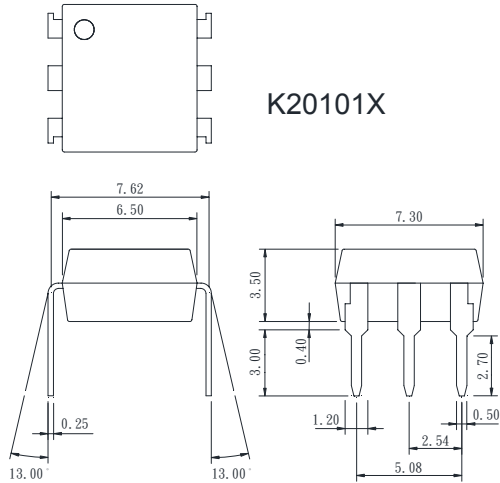
● Applications

- Registers, copies, automatic vending machines
- System appliances, measuring instruments
- Computer terminals, programmable controllers
- Communications, telephone, etc
- Electric home appliances, such as oil fan heaters, microwave oven, washer, refrigerator, air conditioner
- Medical instruments, physical and chemical equipment
- Signal transmission between circuits of different potentials and impedances
- Facsimile equipment, audio, video
- Switching power supply, laser beam printer

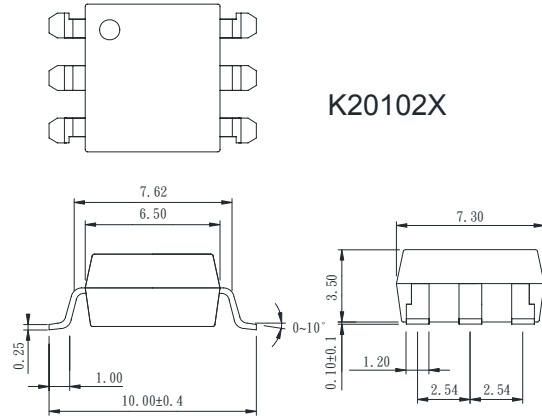
● **Outside Dimension**

Unit : mm

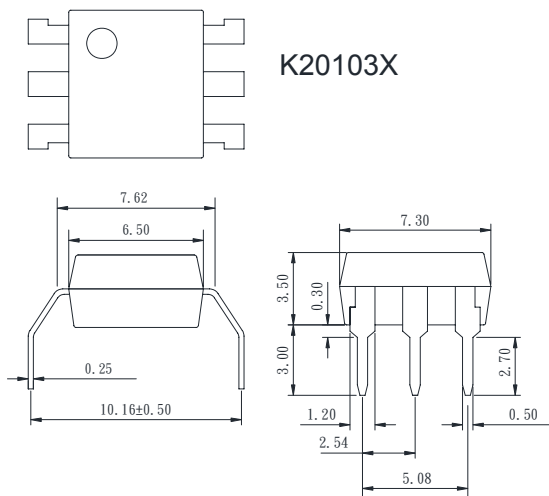
1. Dual-in-line type.



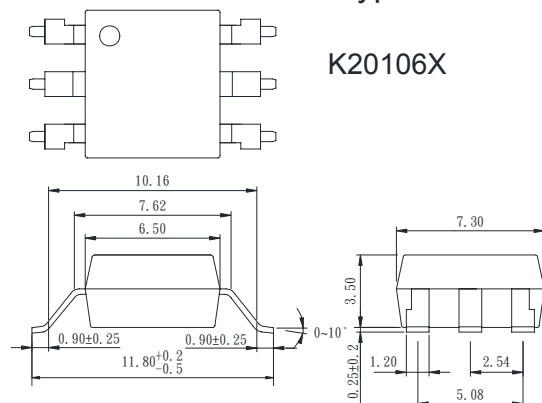
2. Surface mount type.



3. Long creepage distance type

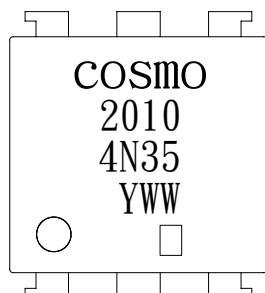


4. Long creepage distance for surface mount type.



TOLERANCE : ±0.2mm

● **Device Marking**



Notes:

COSMO
2010
4N35
YWW



Y: Year code / WW: Week code

□: CTR rank

● **Absolute Maximum Ratings**

(Ta=25°C)

Parameter		Symbol	Rating	Unit
Input	Forward current	I_F	50	mA
	Peak forward current	I_{FM}	1	A
	Reverse voltage	V_R	6	V
	Power dissipation	P_D	70	mW
Output	Collector-emitter voltage	V_{CEO}	80	V
	Emitter-collector voltage	V_{ECO}	6	V
	Collector-base voltage	V_{CBO}	60	V
	Emitter-base voltage	V_{EBO}	6	V
	Collector current	I_C	50	mA
	Collector power dissipation	P_C	150	mW
Total power dissipation		P_{tot}	200	mW
Isolation voltage 1 minute		V_{iso}	5000	Vrms
Operating temperature		T_{opr}	-55 to +115	°C
Storage temperature		T_{stg}	-55 to +125	°C
Soldering temperature 10 seconds		T_{sol}	260	°C

● **Electro-optical Characteristics**

(Ta=25°C)

Parameter		Symbol	Conditions	Min.	Typ.	Max.	Unit
Input	Forward voltage	V_F	$I_F=20mA$	-	1.2	1.4	V
	Peak forward voltage	V_{FM}	$I_{FM}=0.5A$	-	-	3.5	V
	Reverse current	I_R	$V_R=4V$	-	-	10	μA
	Terminal capacitance	C_t	$V=0, f=1KHz$	-	30	-	pF
Output	Collector dark current	I_{CEO}	$V_{CE}=20V, I_F=0$	-	-	0.1	μA
Transfer characteristics	Current transfer ratio	CTR	$I_F=2mA, V_{CE}=5V$	60	-	600	%
	Collector-emitter saturation	$V_{CE(sat)}$	$I_F=20mA, I_C=1mA$	-	0.1	0.3	V
	Isolation resistance	R_{iso}	DC500V	5×10^{10}	10^{11}	-	Ω
	Floating capacitance	C_f	$V=0, f=1MHz$	-	0.6	1.0	pF
	Cut-off frequency	f_c	$V_{CC}=5V, I_C=2mA, R_L=100\Omega$	-	80	-	KHz
	Response time (Rise)	t_r	$V_{CE}=2V, I_C=2mA, R_L=100\Omega$	-	5	20	μs
Response time (Fall)	t_f	-		4	20	μs	

Classification table of current transfer ratio is shown below.

K2010 Model No.	CTR (%)
K2010 A	60 ~ 160
K2010 B	130 ~ 260
K2010 C	200 ~ 400
K2010 D	300 ~ 600
K2010 E	60 ~ 600

Fig.1 Current Transfer Ratio vs. Forward Current

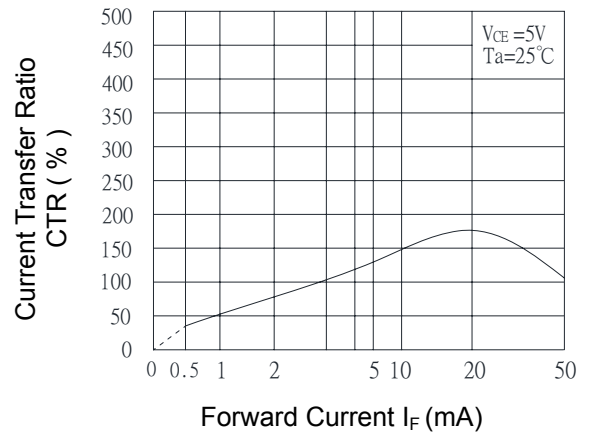


Fig.2 Collector Power Dissipation vs. Ambient Temperature

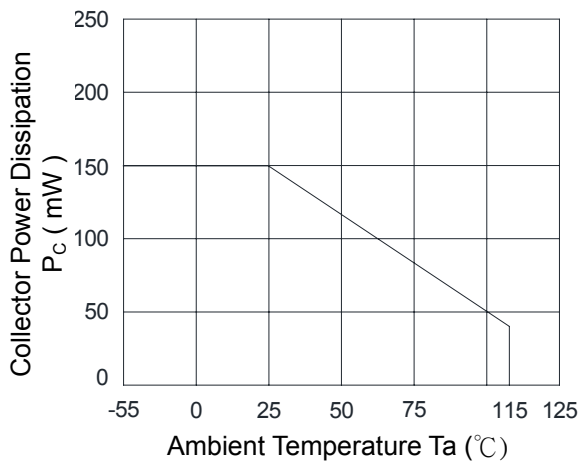


Fig.3 Collector Dark Current vs. Ambient Temperature

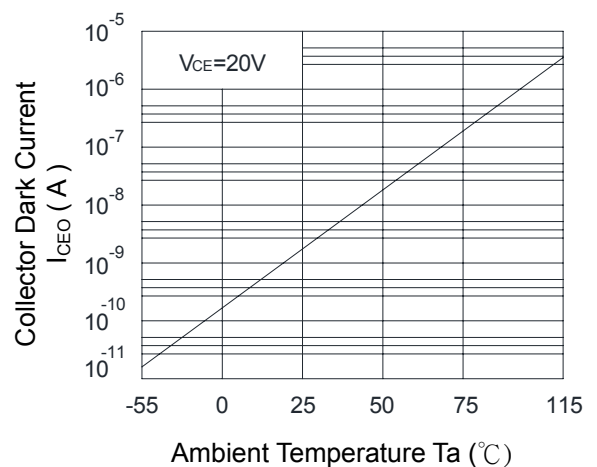


Fig.4 Forward Current vs. Ambient Temperature

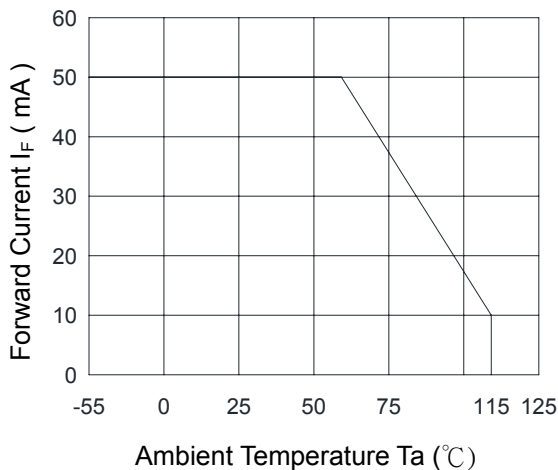


Fig.5 Forward Current vs. Forward Voltage

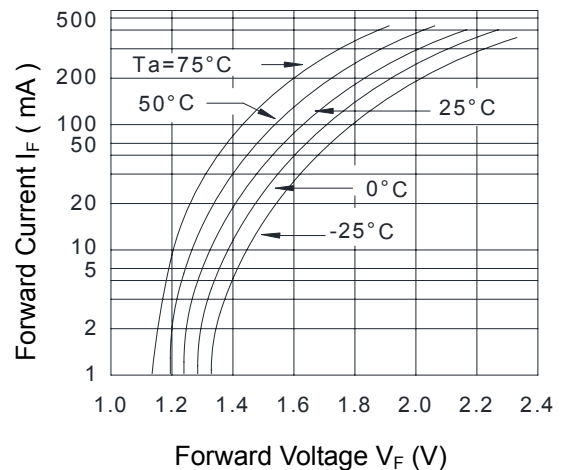


Fig.6 Collector Current vs. Collector-Emitter Voltage

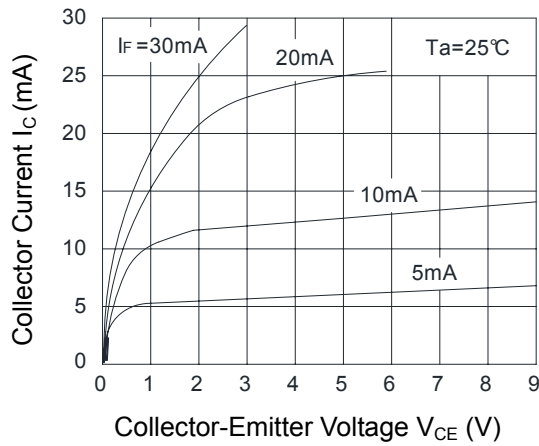


Fig.7 Relative Current Transfer Ratio vs. Ambient Temperature

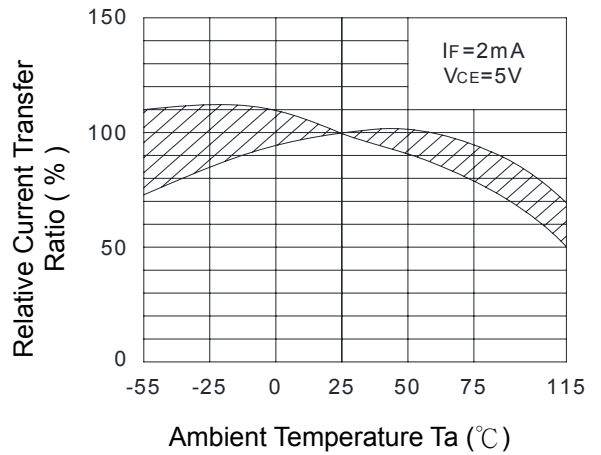


Fig.8 Collector-Emitter Saturation Voltage vs. Ambient Temperature

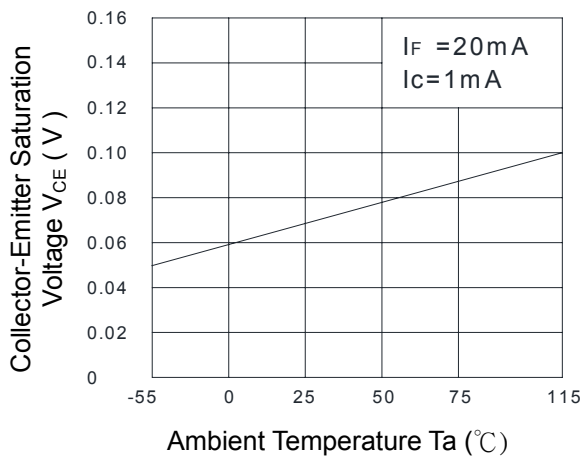


Fig.9 Collector-Emitter Saturation Voltage vs. Forward Current

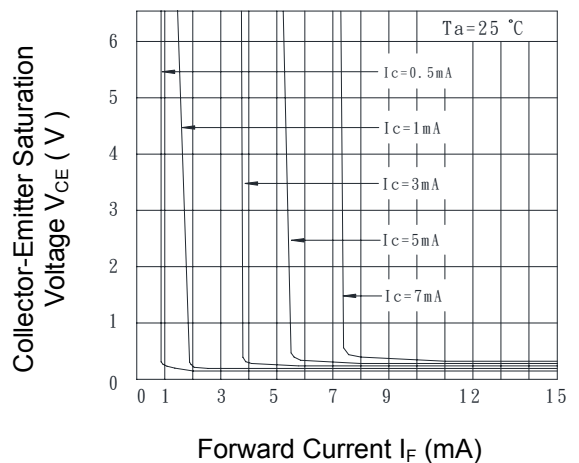


Fig.10 Response Time (Rise) vs. Load Resistance

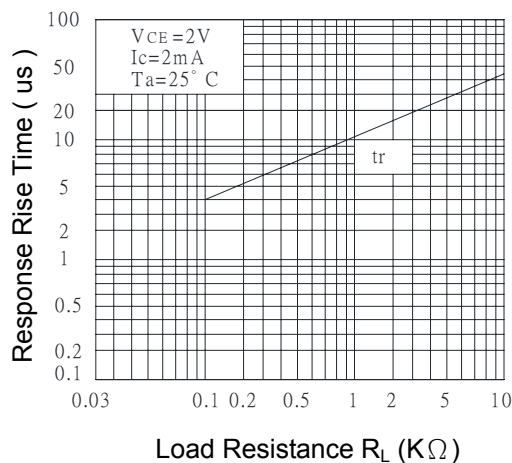
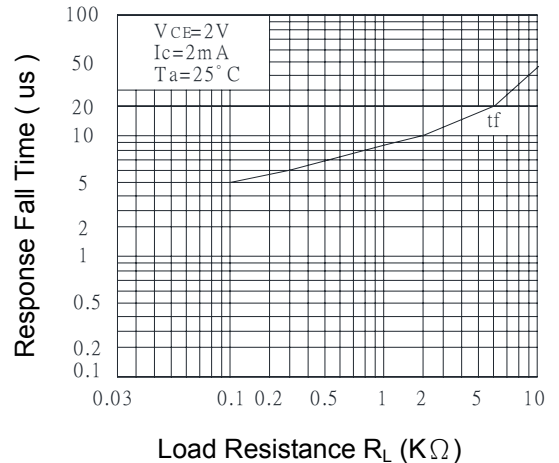
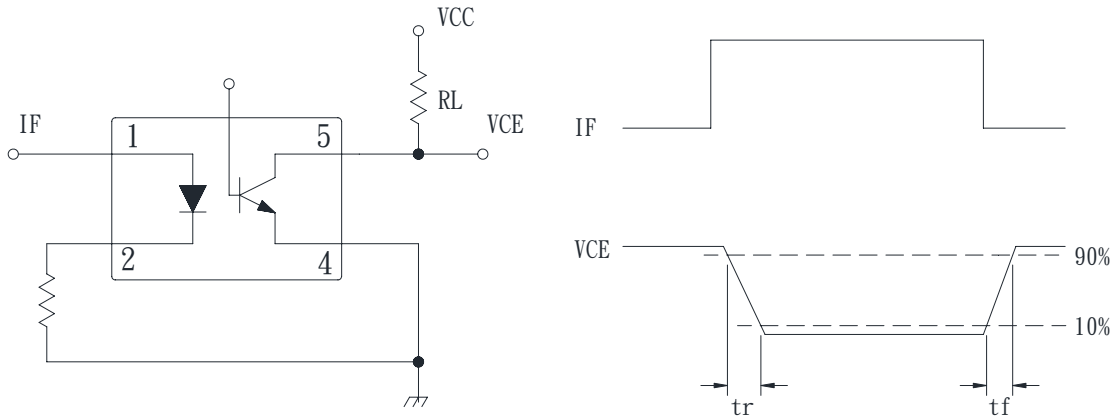


Fig.11 Response Time (Fall) vs. Load Resistance



● **Test Circuit for Response Time**

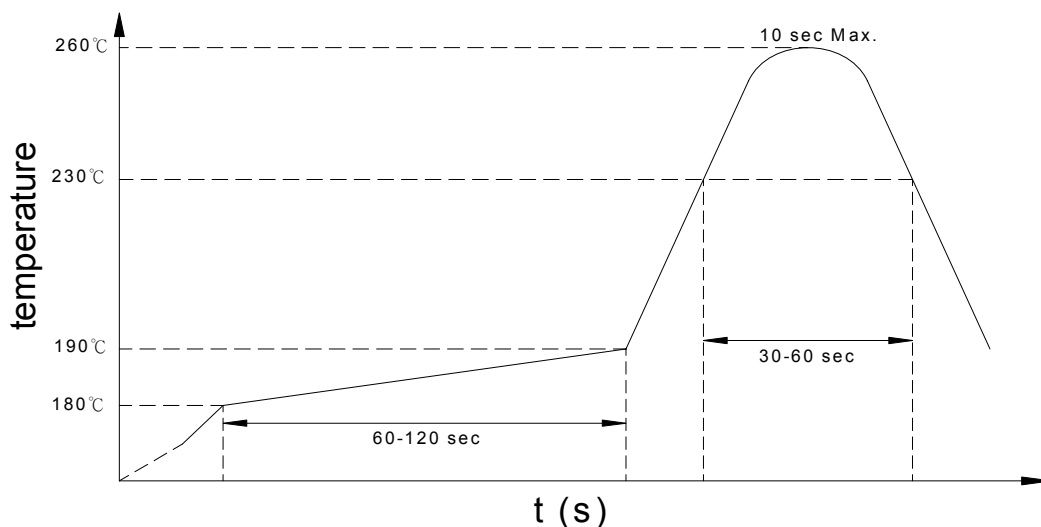


● **Recommended Soldering Conditions**

(a) Infrared reflow soldering :

- Peak reflow soldering : 260°C or below (package surface temperature)
- Time of peak reflow temperature : 10 sec
- Time of temperature higher than 230°C : 30-60 sec
- Time to preheat temperature from 180~190°C : 60-120 sec
- Time(s) of reflow : Two
- Flux : Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

Recommended Temperature Profile of Infrared Reflow



(b) Wave soldering :

- Temperature : 260°C or below (molten solder temperature)
- Time : 10 seconds or less
- Preheating conditions : 120°C or below (package surface temperature)
- Time(s) of reflow : One
- Flux : Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

(c) Cautions :

- Fluxes : Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.
- Avoid shorting between portion of frame and leads.

● **Numbering System**

K2010 X Y (Z)

Notes:

K2010 = Part No.

X = Lead form option (1,2,3,6)

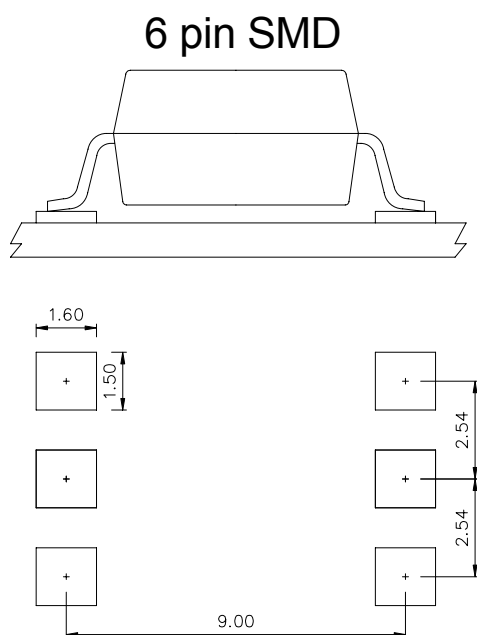
Y = CTR rank option (A ~ E)

Z = Tape and reel option (TL,TR,TLD,TRU)

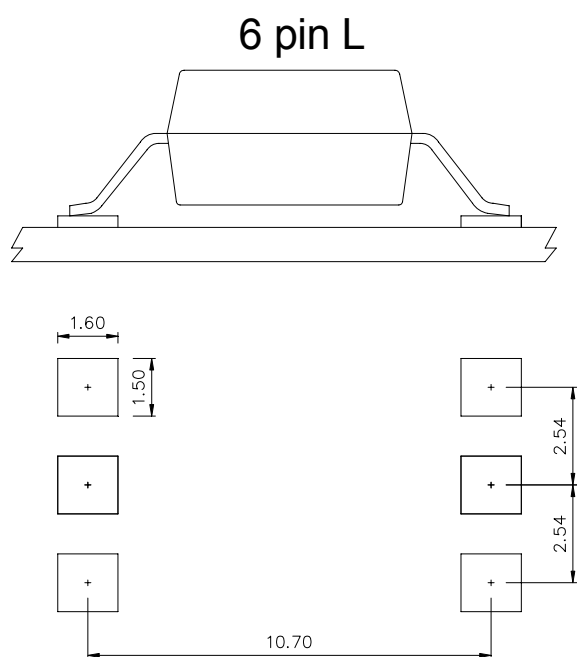
Option	Description	Packing quantity
2 (TL)	surface mount type package + TL tape & reel option	1000 units per reel
2 (TR)	surface mount type package + TR tape & reel option	1000 units per reel
6 (TLD)	long creepage distance for surface mount type package + TLD tape & reel option	1000 units per reel
6 (TRU)	long creepage distance for surface mount type package + TRU tape & reel option	1000 units per reel

● **Recommended Pad Layout for Surface Mount Lead Form**

1. Surface mount type.

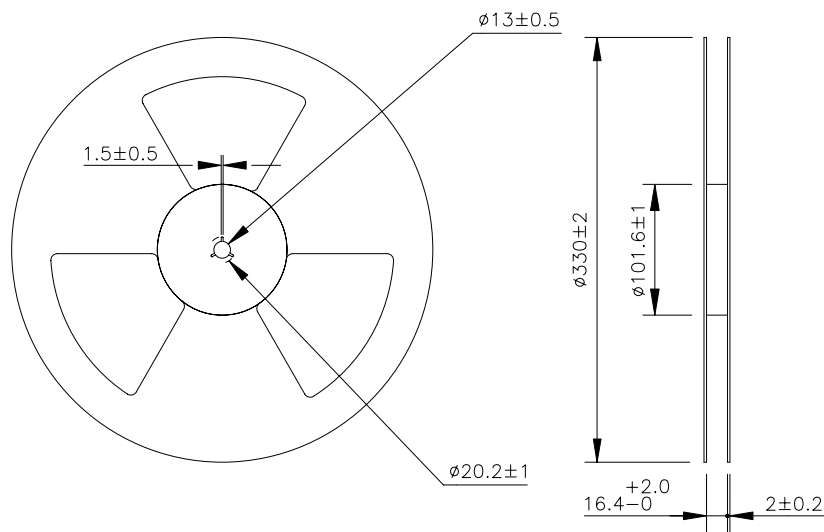
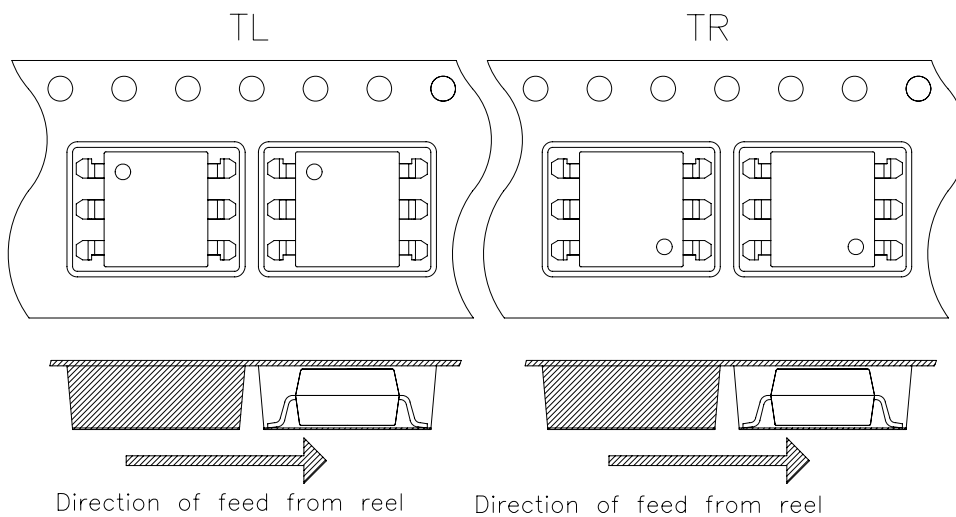
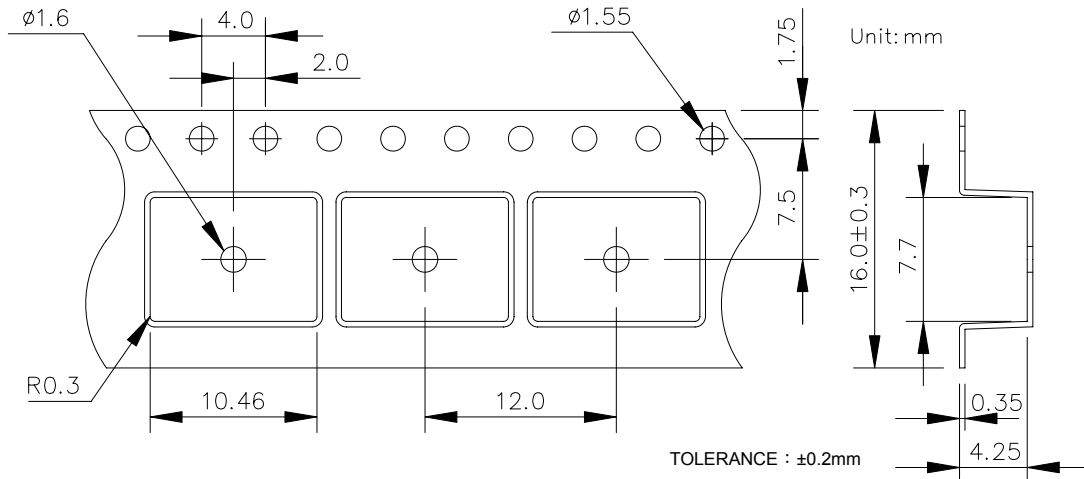


2. Long creepage distance for surface mount type.

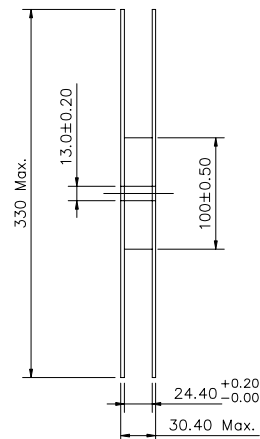
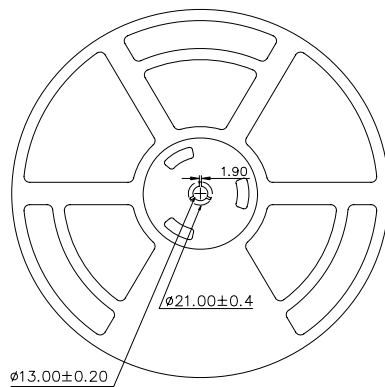
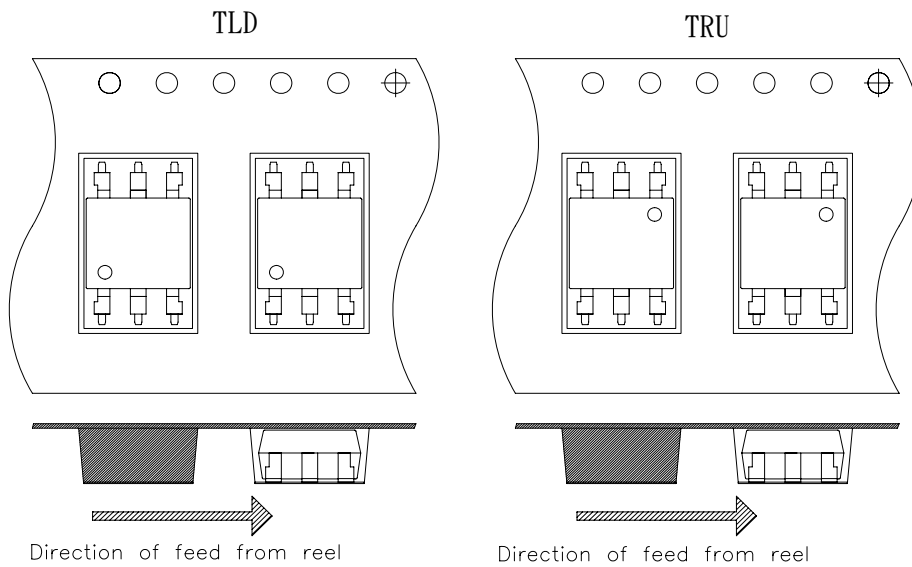
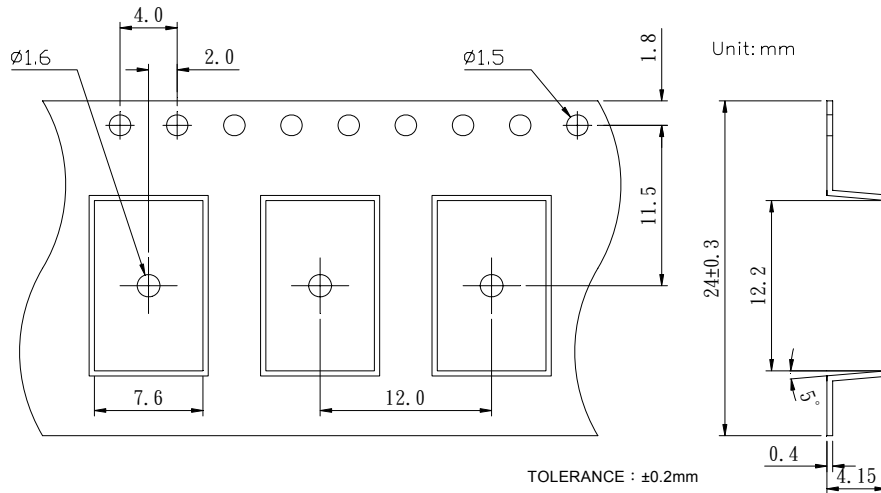


Unit : mm

● **6-pin SMD Carrier Tape & Reel**



● **6-pin L Carrier Tape & Reel**



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